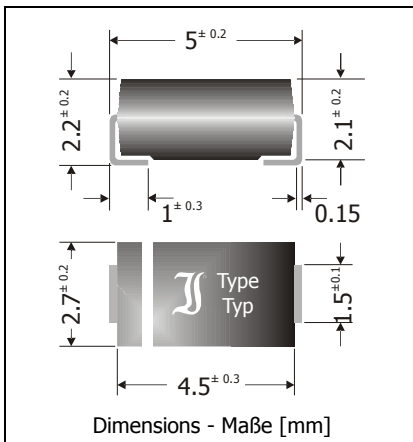



SK12 ... SK115

Surface Mount Schottky Rectifier Diodes Schottky-Gleichrichterdiodes für die Oberflächenmontage

Version 2014-07-03



Nominal current Nennstrom	1 A
Repetitive peak reverse voltage Periodische Spitzensperrspannung	20...150 V
Plastic case Kunststoffgehäuse	~ SMA ~ DO-214AC
Weight approx. – Gewicht ca.	0.07g
Plastic material has UL classification 94V-0 Gehäusematerial UL94V-0 klassifiziert	
Standard packaging taped and reeled Standard Lieferform gegurtet auf Rolle	

Maximum ratings

Grenzwerte

Type Typ	Repetitive peak reverse voltage Periodische Spitzensperrspannung V_{RRM} [V]	Surge peak reverse voltage Stoßspitzensperrspannung V_{RSM} [V]	Forward voltage Durchlass-Spannung V_F [V] ¹⁾
SK12	20	20	< 0.50
SK13	30	30	< 0.50
SK14	40	40	< 0.50
SK15	50	50	< 0.70
SK16	60	60	< 0.70
SK18	80	80	< 0.85
SK110	100	100	< 0.85
SK115	150	150	< 0.85

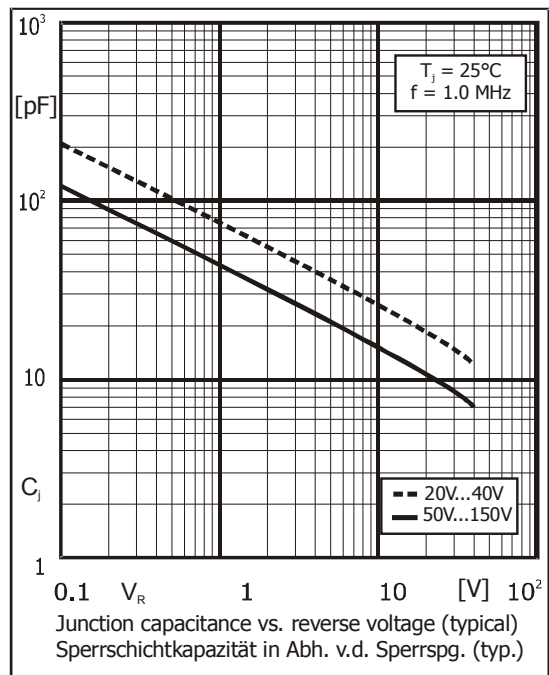
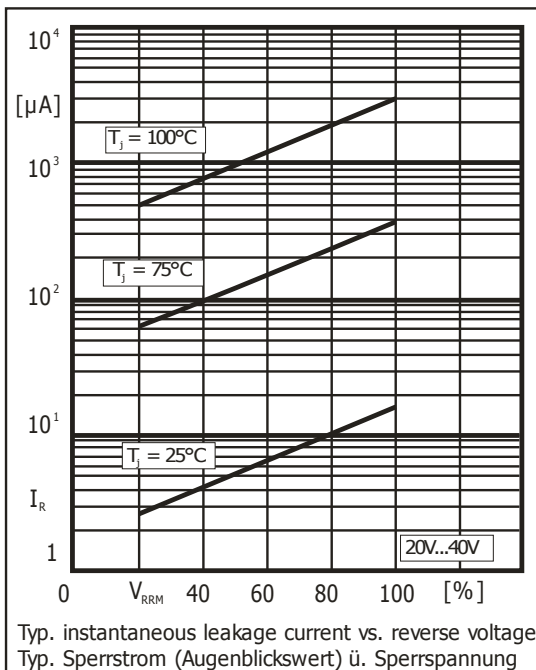
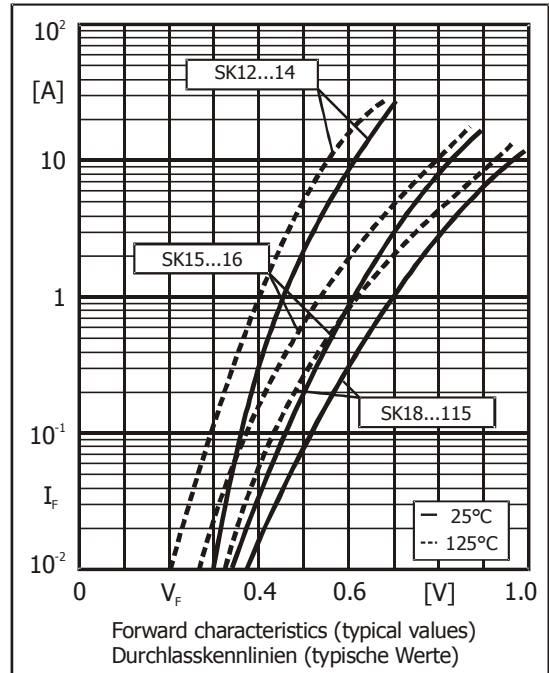
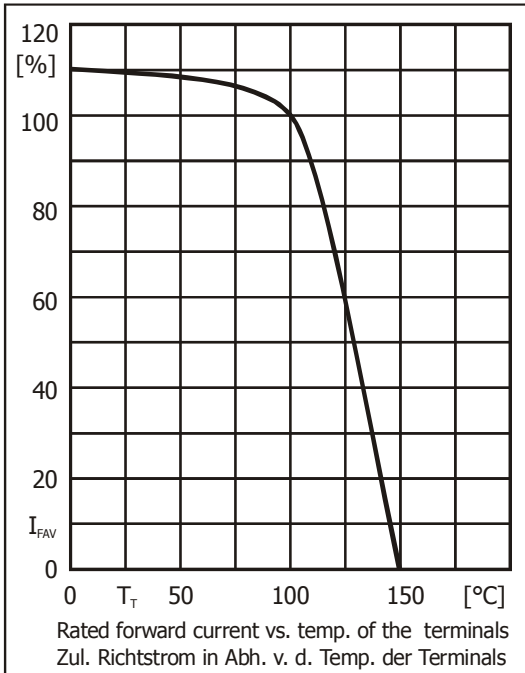
Max. average forward rectified current, R-load Dauergrenzstrom in Einwegschaltung mit R-Last	$T_T = 100^\circ\text{C}$	I_{FAV}	1 A
Repetitive peak forward current Periodischer Spitzenstrom	$f > 15$ Hz	I_{FRM}	6 A ²⁾
Peak forward surge current, 50/60 Hz half sine-wave Stoßstrom für eine 50/60 Hz Sinus-Halbwellen	$T_A = 25^\circ\text{C}$	I_{FSM}	30/33 A
Rating for fusing, $t < 10$ ms Grenzlastintegral, $t < 10$ ms	$T_A = 25^\circ\text{C}$	i^2t	4.5 A ² s
Operating junction temperature – Sperrschichttemperatur Storage temperature – Lagerungstemperatur		T_j T_s	-50...+150°C -50...+150°C

1 $I_F = 1$ A, $T_j = 25^\circ\text{C}$

2 Max. temperature of the terminals $T_T = 100^\circ\text{C}$ – Max. Temperatur der Anschlüsse $T_T = 100^\circ\text{C}$

Characteristics
Kennwerte

Leakage current Sperrstrom	SK12 ... SK110	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$	I_R	< 0.5 mA
	SK115				< 0.2 mA
	SK12 ... SK110	$T_j = 100^\circ\text{C}$	$V_R = V_{RRM}$	I_R	< 5.0 mA
	SK115				< 2.0 mA
Thermal resistance junction to ambient air Wärmewiderstand Sperrschicht – umgebende Luft				R_{thA}	< 70 K/W ¹⁾
Thermal resistance junction to terminal Wärmewiderstand Sperrschicht – Anschluss				R_{thT}	< 30 K/W



1 Mounted on P.C. board with 25 mm² copper pads at each terminal
Montage auf Leiterplatte mit 25 mm² Kupferbelag (Löt-pad) an jedem Anschluss